

**SEMICONDUCTOR INTEGRATED CIRCUIT CARD MANUFACTURING
METHOD, AND SEMICONDUCTOR INTEGRATED CIRCUIT CARD**

ABSTRACT OF THE DISCLOSURE

A semiconductor integrated circuit card is disclosed in which such a semiconductor integrated circuit chip device comprising a substrate having a circuit pattern formed thereon, a semiconductor circuit chip bonded onto the substrate and having an electrode connected to the circuit pattern, a reinforcement metal plate, and a seal resin portion for covering a peripheral face of the semiconductor integrated circuit chip and sticking the reinforcement metal plate onto the semiconductor integrated circuit chip is mounted within a card substrate.

Figure 3



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